ATTY. DOCKET NO.:	APPLICATION SERIAL NO.:
4717-11800	10/686,084
APPLICANT: Bruno GHYSELEN et al.	
FILING DATE: October 14, 2003	GROUP: ~~2812~~ 2823

LIST OF REFERENCES CITED BY APPLICANT

(Use several sheets if necessary)

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U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
TWP	AA	6,569,748 B1	5/2003	Sakaguchi et al.	~~438~~	~~455~~	
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	AE						
	AF						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES	TRANSLATION NO
TWP	AG	EP 0 867 921 A2	3/1999	Europe			X	
TWP	AH	EP 0 1 174 926 A1	1/2002	Europe			X	
	AI							

OTHER REFERENCES (*Including Author, Title, Date, Pertinent Pages, Etc.*)

	AJ	~~Qui-Y. Tong et al., "Low Temperature Wafer Direct Bonding", Journal of Microelectromechanical Systems, Vol. 3, No. 1, March 1994, pages 29-35.~~ copy of IDS 11/04/03
	AK	
	AL	
	AM	

EXAMINER	DATE CONSIDERED
	03/07/05

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U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO

OTHER REFERENCES *(Including Author, Title, Date, Pertinent Pages, Etc.)*

WP	AA	Qui-Y. Tong et al., "Low Temperature Wafer Direct Bonding", Journal of Microelectromechanical Systems, Vol. 3, No. 1, March 1994, pages 29-35.

EXAMINER	DATE CONSIDERED
[signature]	03/07/05

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ATTY. DOCKET NO.:	APPLICATION SERIAL NO.:
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*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
TwP	AA	6,100,166	8/2000	Sakaguchi et al.	438	~~455~~	
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TwP	AG	FR2797714 English Abstract	10/2002	France			X	
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	AI							

OTHER REFERENCES *(Including Author, Title, Date, Pertinent Pages, Etc.)*

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EXAMINER	DATE CONSIDERED
[signature]	03/08/05

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